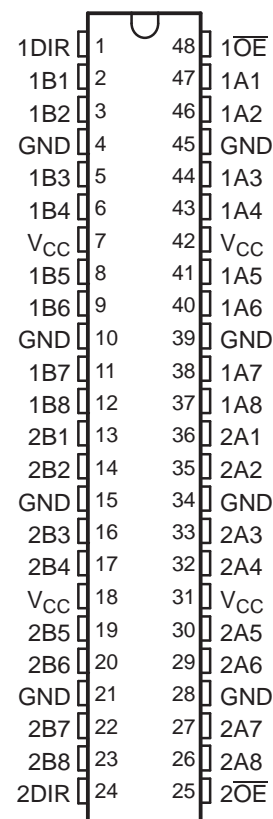


FEATURES

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

SN54LVTH16245A . . . WD PACKAGE
SN74LVTH16245A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The 'LVTH16245A devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The devices are designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input and the output-enable (\overline{OE}) input activate either the B-port outputs or the A-port outputs or place both output ports into the high-impedance mode. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports is always active and must have a logic HIGH or LOW level applied to prevent excess I_{CC} and I_{CCZ} .

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

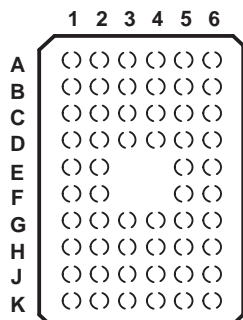
SCBS143R – MAY 1992 – REVISED NOVEMBER 2006

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	FBGA – GRD	Reel of 1000	SN74LVTH16245AGRDR	LL245A
	FBGA – ZRD (Pb-free)		SN74LVTH16245AZRDR	
	SSOP – DL	Tube of 25	74LVTH16245ADL	LVTH16245A
			74LVTH16245ADLG4	
		Reel of 1000	74LVTH16245ADLR	
			74LVTH16245ADLRG4	
	TSSOP – DGG	Reel of 2000	SN74LVTH16245ADGGR	LVTH16245A
			74LVTH16245ADGGRE4	
			74LVTH16245ADGGRG4	
	TVSOP – DGV	Reel of 2000	SN74LVTH16245ADGVR	LL245A
74LVTH16245ADGVRE4				
-55°C to 125°C	VFBGA – GQL	Reel of 1000	SN74LVTH16245AGQLR	LL245A
	VFBGA – ZQL (Pb-free)		74LVTH16245AZQLR	
	CFP – WD	Tube	SNJ54LVTH16245AWD	SNJ54LVTH16245AWD

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

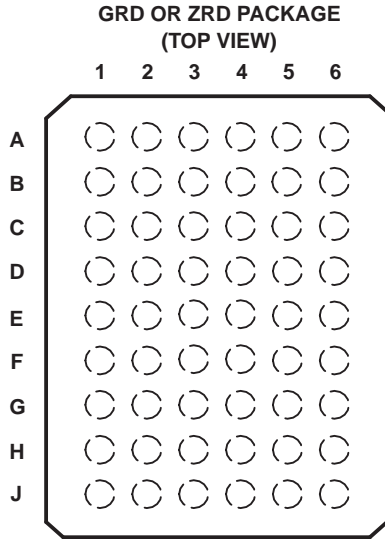
GQL OR ZQL PACKAGE (TOP VIEW)



TERMINAL ASSIGNMENTS⁽¹⁾ (56-Ball GQL/ZQL Package)

	1	2	3	4	5	6
A	1DIR	NC	NC	NC	NC	1 \overline{OE}
B	1B2	1B1	GND	GND	1A1	1A2
C	1B4	1B3	V _{CC}	V _{CC}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
H	2B5	2B6	V _{CC}	V _{CC}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 \overline{OE}

(1) NC – No internal connection



TERMINAL ASSIGNMENTS⁽¹⁾
(54-Ball GRD/ZRD Package)

	1	2	3	4	5	6
A	1B1	NC	1DIR	1 \overline{OE}	NC	1A1
B	1B3	1B2	NC	NC	1A2	1A3
C	1B5	1B4	V _{CC}	V _{CC}	1A4	1A5
D	1B7	1B6	GND	GND	1A6	1A7
E	2B1	1B8	GND	GND	1A8	2A1
F	2B3	2B2	GND	GND	2A2	2A3
G	2B5	2B4	V _{CC}	V _{CC}	2A4	2A5
H	2B7	2B6	NC	NC	2A6	2A7
J	2B8	NC	2DIR	2 \overline{OE}	NC	2A8

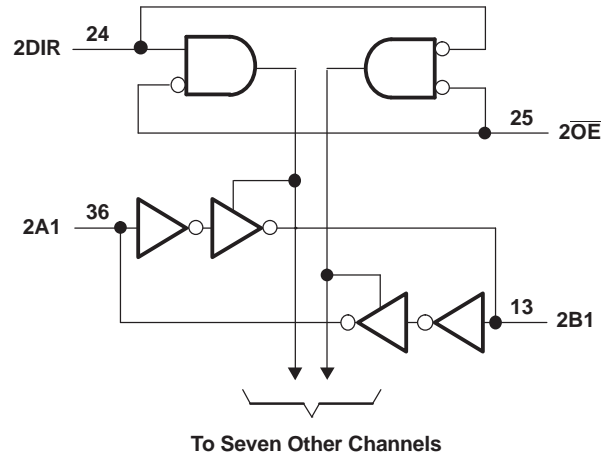
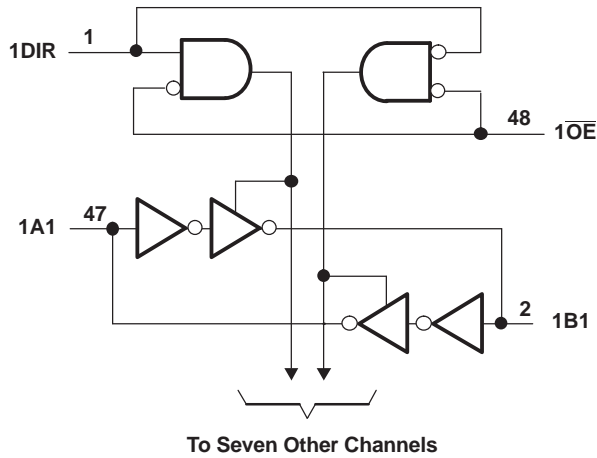
(1) NC – No internal connection

FUNCTION TABLE⁽¹⁾
(EACH 8-BIT SECTION)

CONTROL INPUTS		OUTPUT CIRCUITS		OPERATION
\overline{OE}	DIR	A PORT	B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	H	Hi-Z	Enabled	A data to B bus
H	X	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os always are active.

LOGIC DIAGRAM (POSITIVE LOGIC)



SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS143R–MAY 1992–REVISED NOVEMBER 2006

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	4.6	V
V_I	Input voltage range ⁽²⁾	–0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	7	V
V_O	Voltage range applied to any output in the high state ⁽²⁾	–0.5	$V_{CC} + 0.5$	V
I_O	Current into any output in the low state	SN54LVTH16245A	96	mA
		SN74LVTH16245A	128	
I_O	Current into any output in the high state ⁽³⁾	SN54LVTH16245A	48	mA
		SN74LVTH16245A	64	
I_{IK}	Input clamp current	$V_I < 0$	–50	mA
I_{OK}	Output clamp current	$V_O < 0$	–50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package	70	°C/W
		DGV package	58	
		DL package	63	
		GQL/ZQL package	42	
		GRD/ZRD package	36	
T_{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) This current flows only when the output is in the high state and $V_O > V_{CC}$.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		SN54LVTH16245A		SN74LVTH16245A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage		5.5		5.5	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
	Outputs enabled					
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH16245A			SN74LVTH16245A			UNIT
				MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	
V_{IK}		$V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$		-1.2			-1.2			V
V_{OH}		$V_{CC} = 2.7\text{ V to } 3.6\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$		$V_{CC} - 0.2$			$V_{CC} - 0.2$			V
		$V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$		2.4			2.4			
		$V_{CC} = 3\text{ V}$		2			2			
V_{OL}		$V_{CC} = 2.7\text{ V}$		$I_{OL} = 100\text{ }\mu\text{A}$		0.2			0.2	V
				$I_{OL} = 24\text{ mA}$		0.5			0.5	
		$V_{CC} = 3\text{ V}$		$I_{OL} = 16\text{ mA}$		0.4			0.4	
				$I_{OL} = 32\text{ mA}$		0.5			0.5	
				$I_{OL} = 48\text{ mA}$		0.55				
				$I_{OL} = 64\text{ mA}$					0.55	
I_I		Control inputs $V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}\text{ or GND}$ $V_{CC} = 0\text{ or } 3.6\text{ V}$, $V_I = 5.5\text{ V}$		± 1			± 1			μA
				10			10			
		A or B port ⁽²⁾ $V_{CC} = 3.6\text{ V}$		$V_I = 5.5\text{ V}$		20			20	
				$V_I = V_{CC}$		5			5	
I_{off}		$V_{CC} = 0$, $V_I\text{ or } V_O = 0\text{ to } 4.5\text{ V}$					± 100			μA
$I_{I(\text{hold})}$		$V_{CC} = 3\text{ V}$		$V_I = 0.8\text{ V}$		75			75	μA
				$V_I = 2\text{ V}$		-75			-75	
		$V_{CC} = 3.6\text{ V}$, ⁽³⁾		$V_I = 0\text{ to } 3.6\text{ V}$					500 -750	
I_{OZPU}		$V_{CC} = 0\text{ to } 1.5\text{ V}$, $V_O = 0.5\text{ V to } 3\text{ V}$, $OE = \text{don't care}$		± 100 ⁽⁴⁾			± 100			μA
I_{OZPD}		$V_{CC} = 1.5\text{ V to } 0$, $V_O = 0.5\text{ V to } 3\text{ V}$, $OE = \text{don't care}$		± 100 ⁽⁴⁾			± 100			μA
I_{CC}		$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$		Outputs high		0.19			0.19	mA
				Outputs low		5			5	
				Outputs disabled		0.19			0.19	
ΔI_{CC} ⁽⁵⁾		$V_{CC} = 3\text{ V to } 3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$		0.2			0.2			mA
C_i		$V_I = 3\text{ V or } 0$		4			4			pF
C_{io}		$V_O = 3\text{ V or } 0$		10			10			pF

 (1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

 (2) Unused pins at $V_{CC}\text{ or GND}$

(3) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(4) On products compliant to MIL-PRF-38535, this parameter is not production tested.

 (5) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than $V_{CC}\text{ or GND}$.

SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS143R–MAY 1992–REVISED NOVEMBER 2006

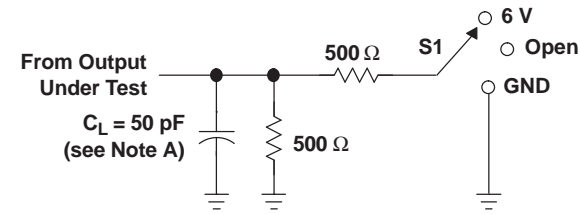
Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH16245A				SN74LVTH16245A				UNIT	
			$V_{CC} = 3.3$ V ± 0.3 V		$V_{CC} = 2.7$ V		$V_{CC} = 3.3$ V ± 0.3 V			$V_{CC} = 2.7$ V		
			MIN	MAX	MIN	MAX	MIN	TYP ⁽¹⁾	MAX	MIN		MAX
t_{PLH}	A or B	B or A	0.5	4.5	4.6		1.5	2.3	3.3	3.7		ns
t_{PHL}			0.5	4.4	3.9		1.3	2.1	3.3	3.5		
t_{PZH}	\overline{OE}	A or B	0.5	6.5	6.6		1.5	2.8	4.5	5.3		ns
t_{PZL}			0.5	5.4	6.2		1.6	2.9	4.6	5.2		
t_{PHZ}	\overline{OE}	A or B	1	6.8	7		2.3	3.7	5.1	5.5		ns
t_{PLZ}			1	6.2	6.3		2.2	3.5	5.1	5.4		
$t_{sk(LH)}$								0.5	0.5		ns	
$t_{sk(HL)}$								0.5	0.5			

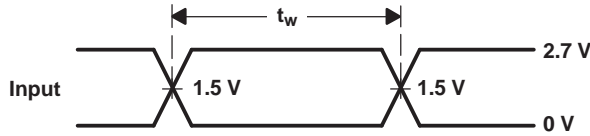
(1) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION

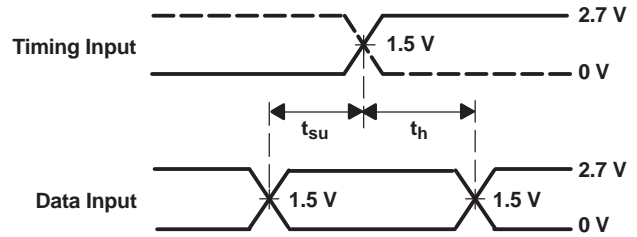


LOAD CIRCUIT

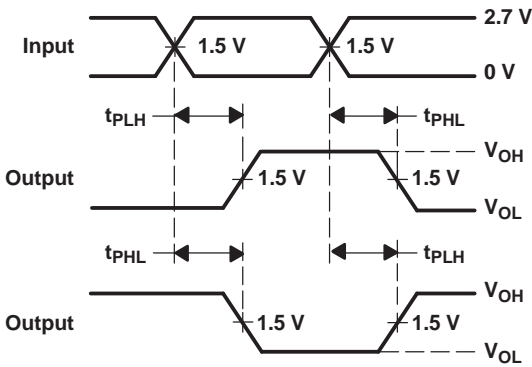
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



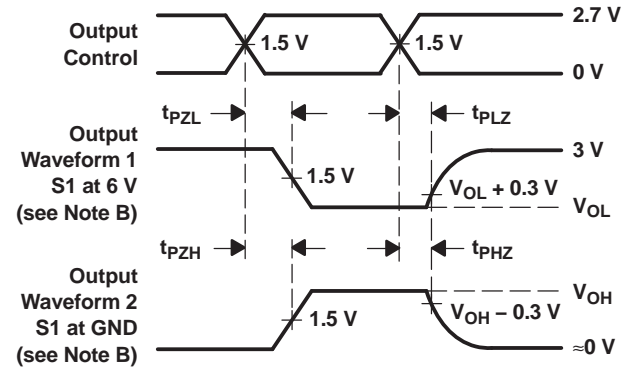
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-9668601QXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Call TI	-55 to 125	5962-9668601QX A SNJ54LVTH16245 AWD	Samples
5962-9668601VXA	ACTIVE	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9668601VX A SNV54LVTH16245 AWD	Samples
74LVTH16245ADGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
74LVTH16245ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
74LVTH16245ADGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
74LVTH16245ADGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
74LVTH16245ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
74LVTH16245ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
SN74LVTH16245ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245AGQLR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85	LL245A	
SN74LVTH16245AGRDR	OBSOLETE	BGA MICROSTAR JUNIOR	GRD	54		TBD	Call TI	Call TI	-40 to 85	LL245A	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74LVTH16245AZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
SN74LVTH16245AZRDR	ACTIVE	BGA MICROSTAR JUNIOR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
SNJ54LVTH16245AWD	ACTIVE	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9668601QX A SNJ54LVTH16245 AWD	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVTH16245A, SN54LVTH16245A-SP, SN74LVTH16245A :

- Catalog: [SN74LVTH16245A](#), [SN54LVTH16245A](#)
- Automotive: [SN74LVTH16245A-Q1](#), [SN74LVTH16245A-Q1](#)
- Enhanced Product: [SN74LVTH16245A-EP](#), [SN74LVTH16245A-EP](#)
- Military: [SN54LVTH16245A](#)
- Space: [SN54LVTH16245A-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16245ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74LVTH16245ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74LVTH16245AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74LVTH16245AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	330.0	16.4	5.8	8.3	1.55	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

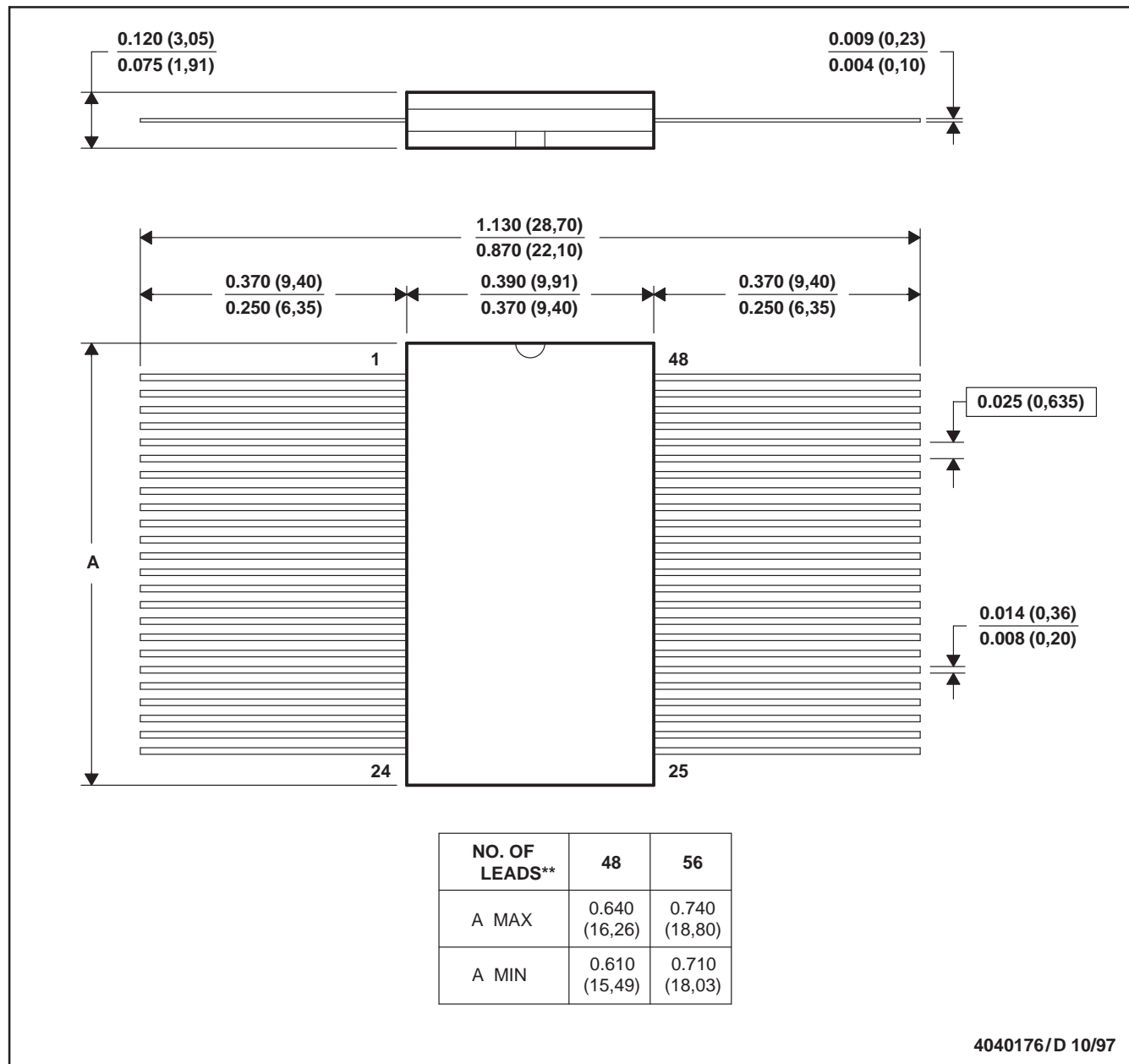

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16245ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74LVTH16245ADLR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74LVTH16245AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	336.6	336.6	28.6
SN74LVTH16245AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	336.6	336.6	28.6

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

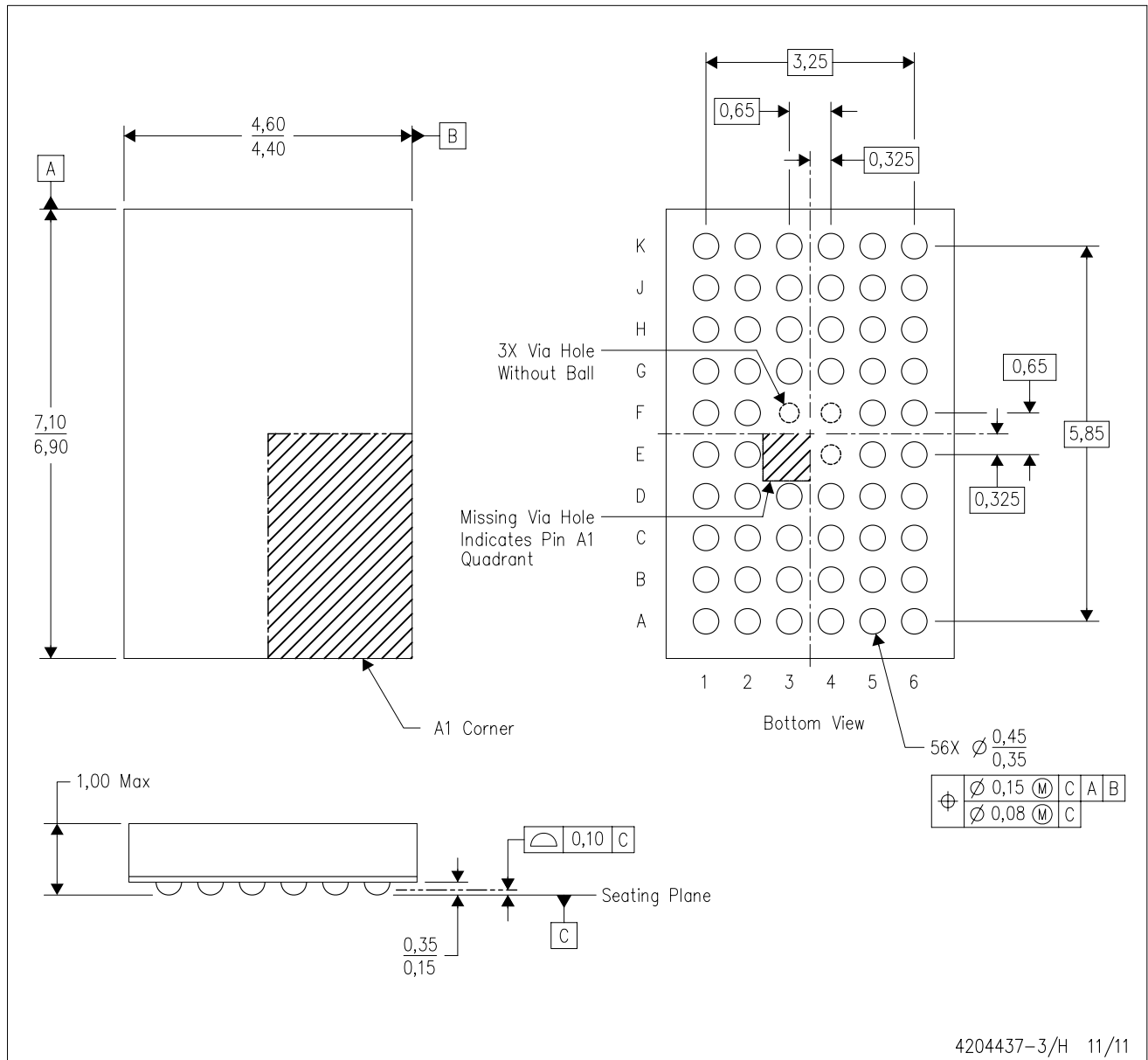
48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 GDFP1-F56 and JEDEC MO-146AB

ZQL (R-PBGA-N56)

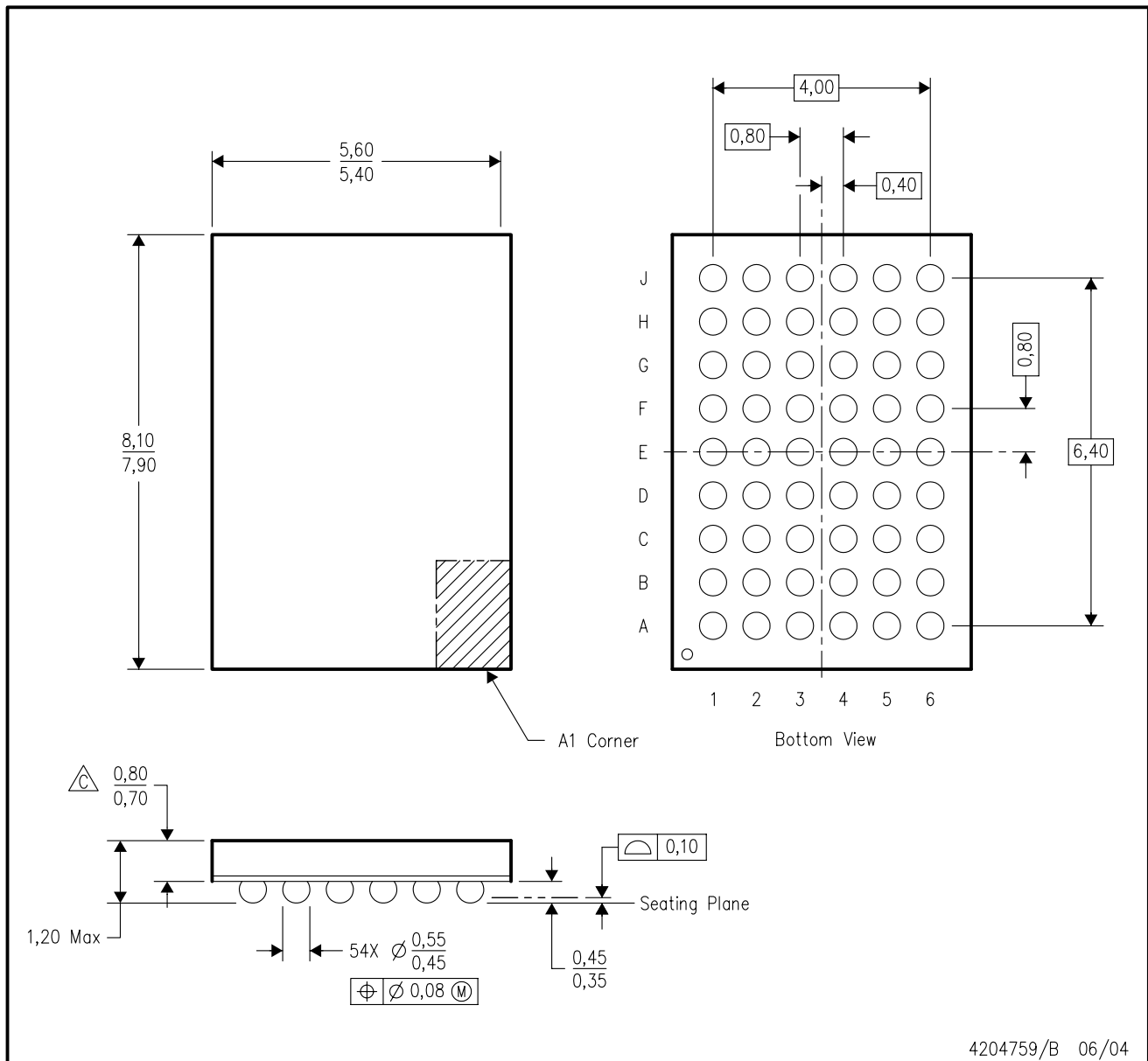
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BA-2.
 - D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

GRD (R-PBGA-N54)

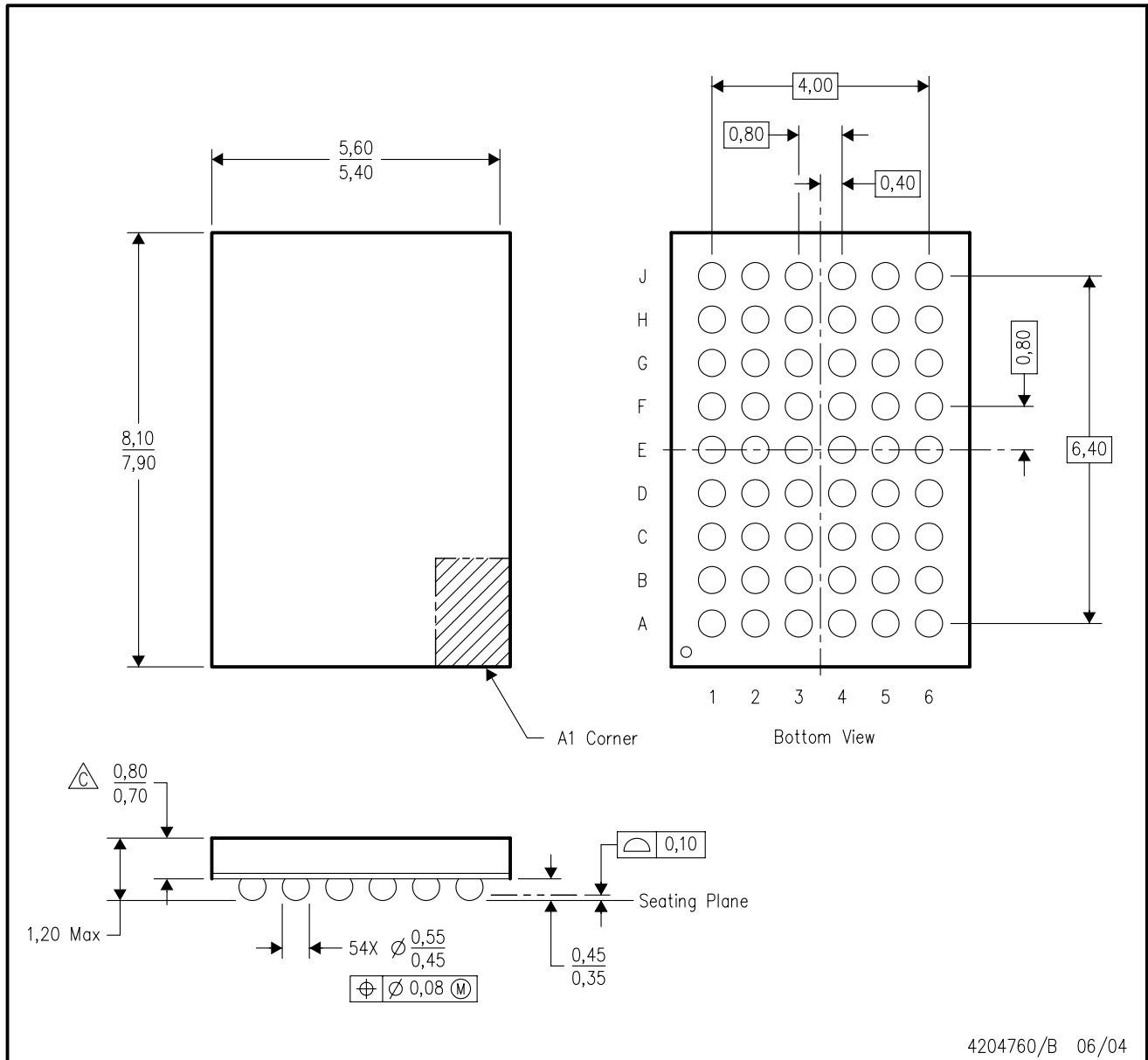
PLASTIC BALL GRID ARRAY




- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MO-205 variation DD.
 - D. This package is tin-lead (SnPb). Refer to the 54 ZRD package (drawing 4204760) for lead-free.

ZRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC M0-205 variation DD.
 - D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

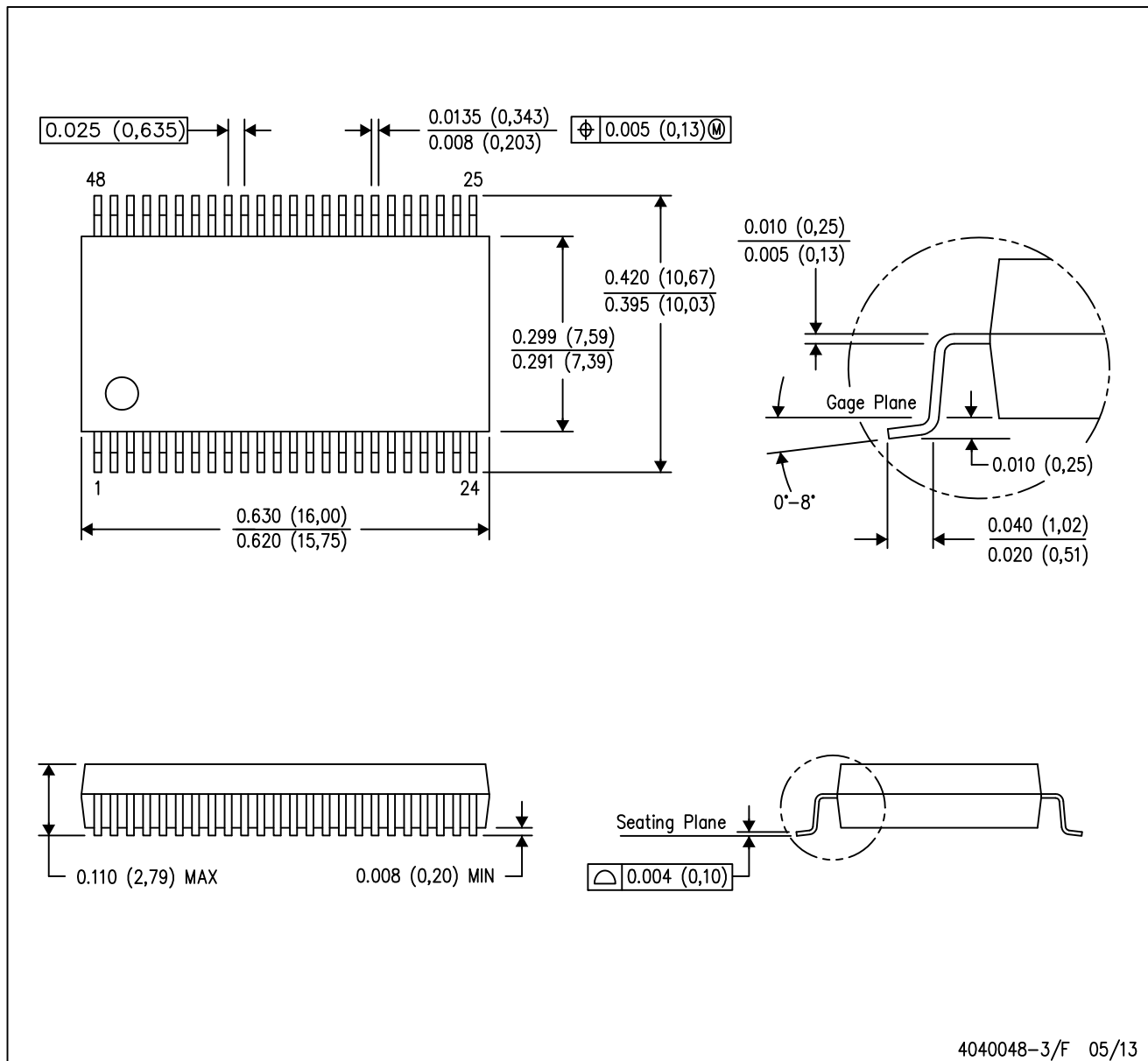


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE

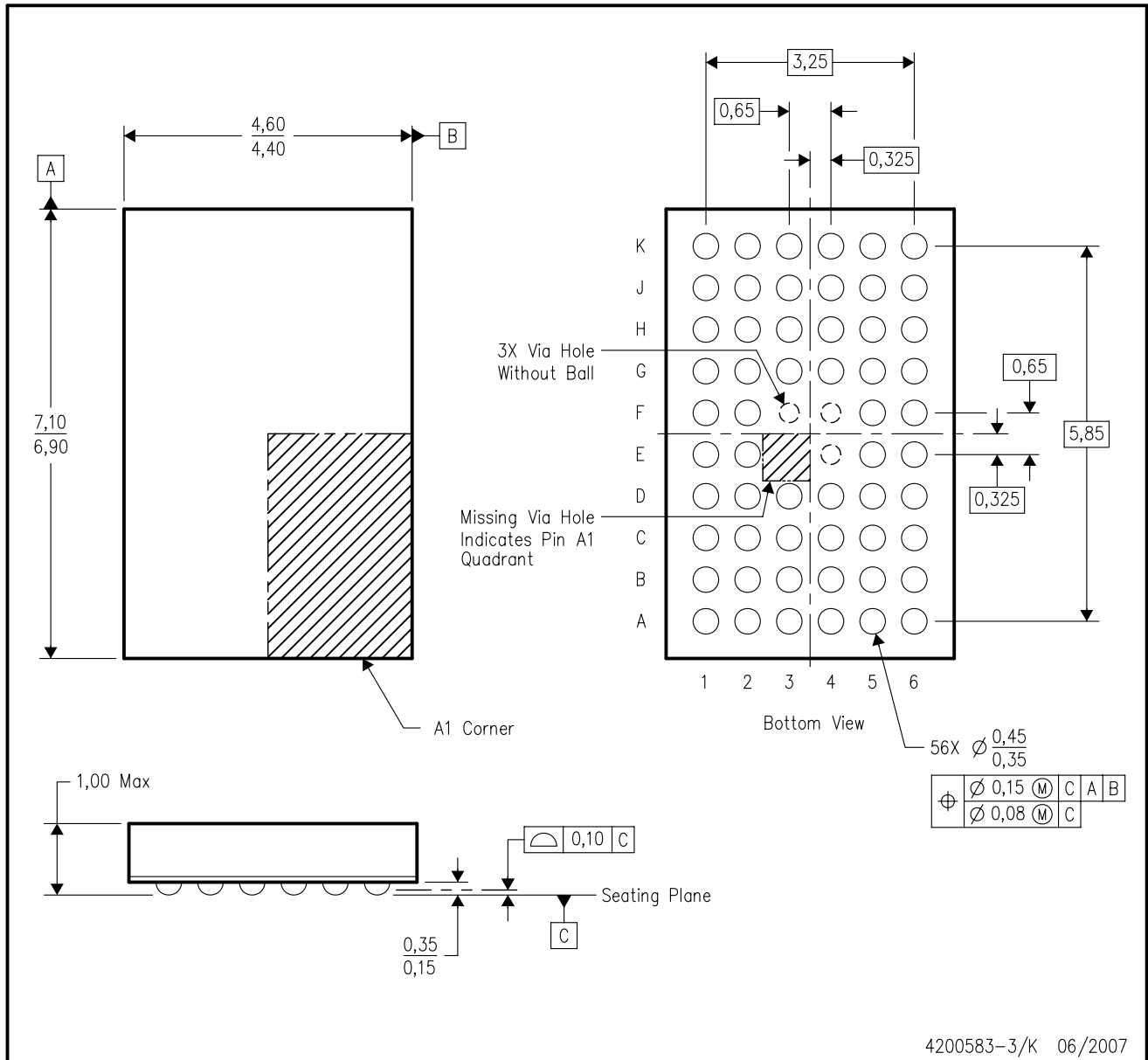


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY

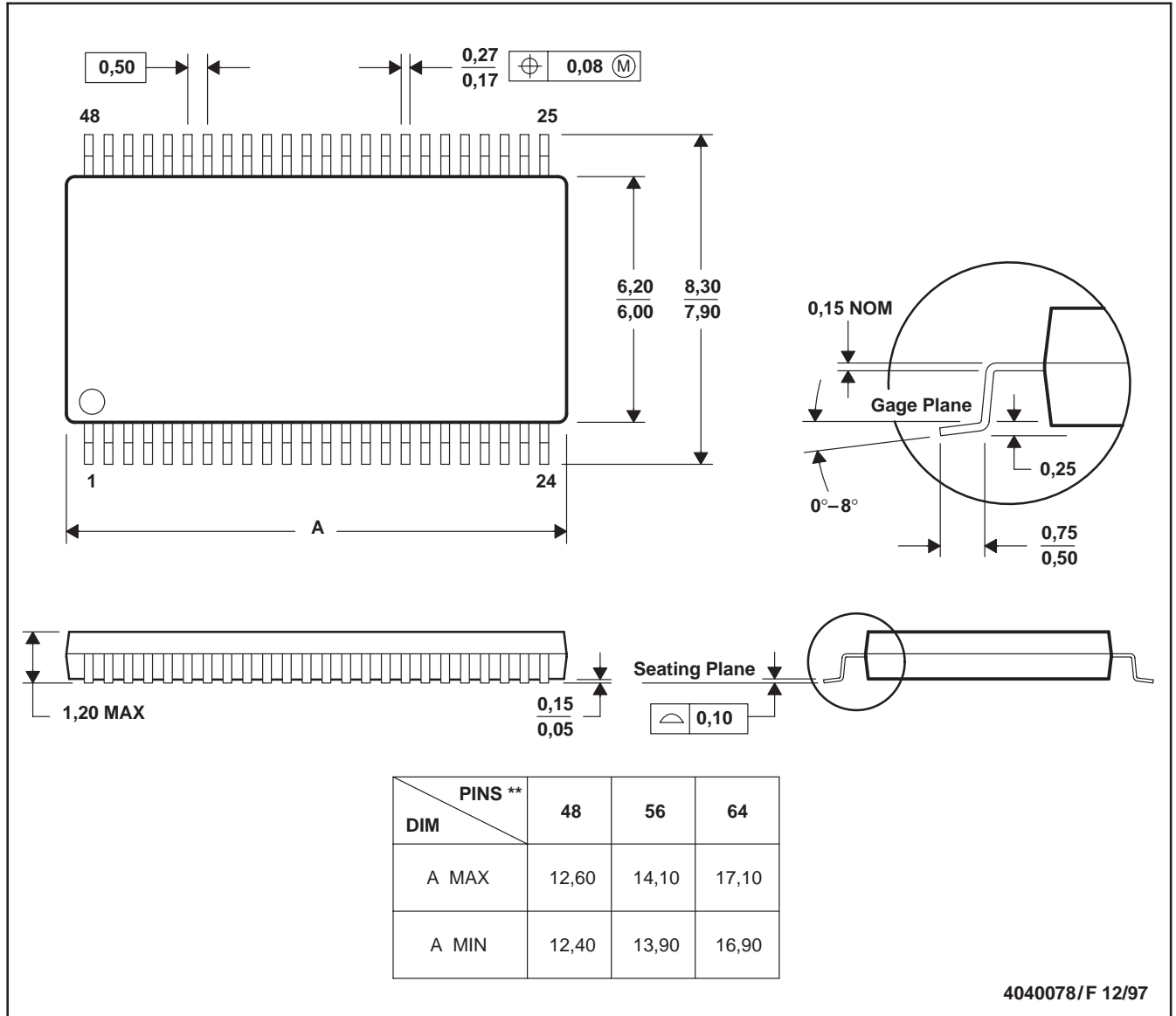


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BA-2.
 - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com